

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT														
NATURE OF CONVEYANCE:	ASSIGNMENT														
CONVEYING PARTY DATA															
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<table border="1"> <tr> <td>Name:</td> <td>Taiwan Semiconductor Manufacturing Company, Ltd.</td> </tr> <tr> <td>Street Address:</td> <td>No. 8, Li-Hsin Road 6</td> </tr> <tr> <td>City:</td> <td>Hsin-Chu</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> <tr> <td>Postal Code:</td> <td>300-77</td> </tr> </table>		Name:	Taiwan Semiconductor Manufacturing Company, Ltd.	Street Address:	No. 8, Li-Hsin Road 6	City:	Hsin-Chu	State/Country:	TAIWAN	Postal Code:	300-77				
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CORRESPONDENCE DATA															
<p>Fax Number: 2142000853 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 214-651-5000 Email: ipdocketing@haynesboone.com Correspondent Name: HAYNES AND BOONE, LLP Address Line 1: 2323 Victory Avenue Address Line 2: Suite 700 Address Line 4: Dallas, TEXAS 75219</p>															
ATTORNEY DOCKET NUMBER:	24061.2313														

NAME OF SUBMITTER:

David M. O'Dell

Total Attachments: 4

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PATENT

REEL: 029123 FRAME: 0235

Docket No.: 2012-0651 / 24061.2258
Customer No.: 42717

ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|------------------|----|--|
| (1) | Ping-Yin Liu | of | 3F, No. 7, Bao-An Road
Yonghe City, Taipei City 234, Taiwan, R.O.C. |
| (2) | Kai-Wen Cheng | of | No. 45-2, Wenchang E 6th Street, Beitun District
Taichung City 406, Taiwan, R.O.C. |
| (3) | Xin-Hua Huang | of | No. 276, Zhonggong Road
Xihu Township, Changhua County 514, Taiwan, R.O.C. |
| (4) | Lan-Lin Chao | of | 3F, No. 113, Zihli Street
Sindian City, Taipei County, Taiwan, R.O.C. |
| (5) | Chia-Shiung Tsai | of | No. 5, Alley 50, Lane 62, Gua-Tsuey Road
Hsin-Chu, Taiwan, R.O.C. |
| (6) | Xiaomeng Chen | of | Room 3309, No. 22, Alley 10, Lane 52, Baoshan Rd., East District
Hsinchu City 300, Taiwan, R.O.C. |

have invented certain improvements in

MULTIPLE METAL LAYER SEMICONDUCTOR DEVICE AND LOW TEMPERATURE STACKING METHOD OF FABRICATING THE SAME

for which we have executed an application for Letters Patent of the United States of America on
October 12, 2012, as U.S. Serial No. 13/651,045; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

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AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Ping-Yin Liu

Residence Address: 3F, No. 7, Bao-An Road
Yonghe City, Taipei City 234, Taiwan, R.O.C.

Dated: 2012. 9. 24.

Ping Yin Liu
Inventor Signature

Inventor Name: Kai-Wen Cheng

Residence Address: No. 45-2, Wenchang E 6th Street, Beitun District
Taichung City 406, Taiwan, R.O.C.

Dated: 2012. 9. 24

Kai-Wen Cheng
Inventor Signature

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Inventor Name: Xin-Hua Huang

Residence Address: No. 276, Zhonggong Road
Xihu Township, Changhua County 514, Taiwan, R.O.C.

Dated: 2012. 9. 24

Xin-Hua Huang
Inventor Signature

Inventor Name: Lan-Lin Chao

Residence Address: 3F, No. 113, Zihli Street
Sindian City, Taipei County, Taiwan, R.O.C.

Dated: 09/24/2012

Lan-Lin Chao
Inventor Signature

Inventor Name: Chia-Shiung Tsai

Residence Address: No. 5, Alley 50, Lane 62, Gua-Tsuey Road
Hsin-Chu, Taiwan, R.O.C.

Dated: 09/24/2012

Chia-Shiung Tsai
Inventor Signature

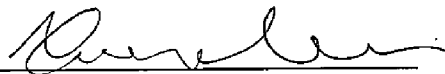
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Inventor Name: Xiaomeng Chen

Residence Address: Room 3309, No. 22, Alley 10, Lane 52, Baoshan Rd., East District
Hsinchu City 300, Taiwan, R.O.C.

Dated: _____

09/27/12


Inventor Signature